

## Solder Wire Sn99.3/Cu0.7 No-Clean with 2.0% Flux Core 4oz Spool

### Product Highlights

#### No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.0% flux core

Halogen content: None

**RoHS 3 and REACH compliant**

### Specifications

|                      |                    |
|----------------------|--------------------|
| Alloy:               | Sn99.3/Cu0.7       |
| Wire Diameter:       | 0.015" (0.38mm)    |
| Flux Type:           | No-Clean Synthetic |
| Flux Classification: | ROL0               |
| Melting Point:       | 227°C (441°F)      |
| Packaging:           | 4 oz spool         |



### Test Results

| Test J-STD-004 or other requirements as stated         | Test Requirement                                   | Result                                                                                             |
|--------------------------------------------------------|----------------------------------------------------|----------------------------------------------------------------------------------------------------|
| Copper Mirror                                          | IPC-TM-650: 2.3.32                                 | L: No breakthrough                                                                                 |
| Corrosion                                              | IPC-TM-650: 2.6.15                                 | L: No corrosion                                                                                    |
| Quantitative Halides                                   | IPC-TM-650: 2.3.28.1                               | L: <0.5%                                                                                           |
| Electrochemical Migration                              | IPC-TM-650: 2.6.14.1                               | L: <1 decade drop (No-clean)                                                                       |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours | IPC-TM-650: 2.6.3.7                                | L: ≥100MΩ (No-clean)                                                                               |
| Visual                                                 | IPC-TM-650: 3.4.2.5                                | Clear and free from precipitation                                                                  |
| Conflict Minerals Compliance                           | Electronic Industry Citizenship Coalition (EICC)   | Compliant                                                                                          |
| REACH Compliance                                       | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

### Conforms to the following Industry Standards:

|                                                                             |     |
|-----------------------------------------------------------------------------|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes):                                    | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 3 Directive (EU) 2015/863:                                             | Yes |